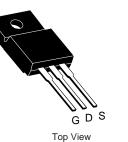
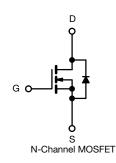


H7N0608FM-VB Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT	RODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a			
60	0.005 at V _{GS} = 10 V	120			
00	0.013 at V _{GS} = 4.5 V	95			

TO-220 FULLPAK





• 175 °C Junction Temperature

- Trench Power MOSFETMaterial categorization:



ABSOLUTE MAXIMUM RATINGS (T _C =	25 °C, unless othe	rwise noted)			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage	ate-Source Voltage		± 20		
Continuous Drain Current (T 175 °C)b	T _C = 25 °C	L	120		
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^{b}$	T _C = 100 °C	I _D	95 ^a		
Pulsed Drain Current		I _{DM}	300	А	
Continuous Source Current (Diode Conduction)		۱ _S	70 ^a		
Avalanche Current			50		
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	125	mJ	
Movimum Douter Discipation	T _C = 25 °C	P	136	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	3 ^b , 8.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Mauinung lungting to Archigged	t ≤ 10 sec	R _{thJA}	15	18	
Maximum Junction-to-Ambient ^a	Steady State	'`thJA	40	50	°C/W
Maximum Junction-to-Case		R _{thJC}	0.85	1.1	
Notes:					

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t ≤ 10 s.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static	.,			1961			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	60				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$ 1		3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50		
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	60			А	
		V _{GS} = 10 V, I _D = 20 A		0.005			
	Р	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.010		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.015			
		V _{GS} = 4.5 V, I _D = 15 A		0.013		1	
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic			•				
Input Capacitance	C _{iss}			5650			
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		1120		pF	
Reverse Transfer Capacitance	C _{rss}			525		1	
Total Gate Charge ^c	Qg			47	70		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_D = 50 A		10		nC	
Gate-Drain Charge ^c	Q _{gd}			12			
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r			15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}	ff) $I_D \cong 50$ A, $V_{GEN} = 10$ V, $R_g = 2.5$ Ω		35	50	115	
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)	-				
Pulsed Current	I _{SM}			3 0 0		А	
Diode Forward Voltage	V_{SD}	$I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns	

SPECIFICATIONS ($T_1 = 25 \,^{\circ}C_2$, unless otherwise noted)

Notes:

a. For design aid only; not subject to production testing.

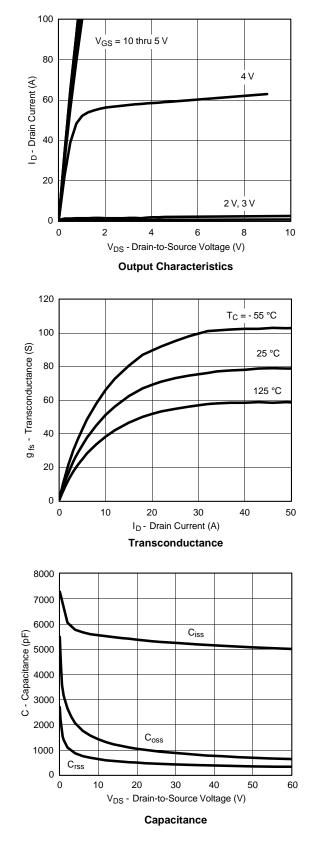
b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

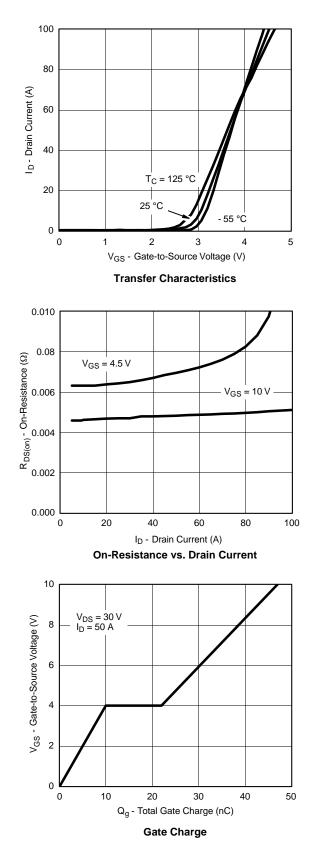
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



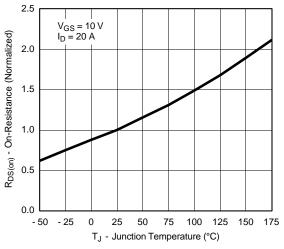
TYPICAL CHARACTERISTICS (25 °C unless noted)



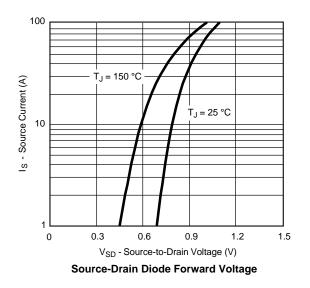




TYPICAL CHARACTERISTICS (25 °C unless noted)

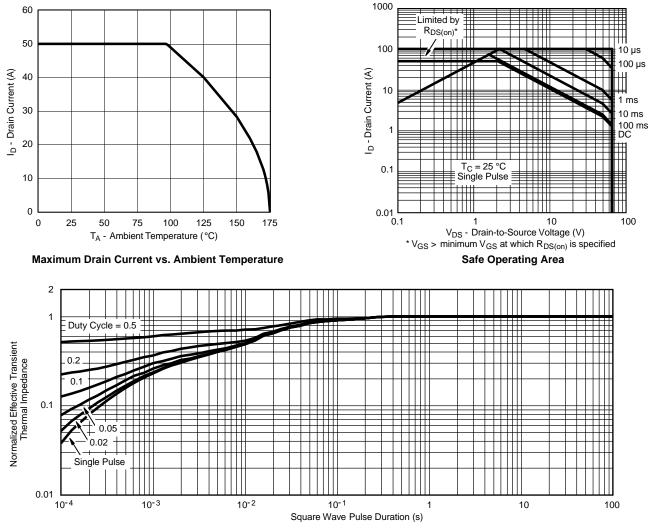


On-Resistance vs. Junction Temperature





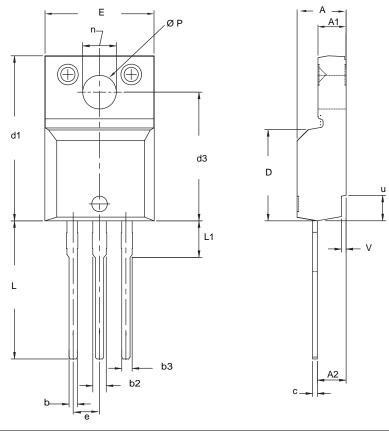
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



	MILLI	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet $C_{pk} > 1.33$. 4. All dimensions include burrs and plating thickness. 5. No chipping or package damage.



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